

Title (en)
METHOD OF ADDING FABRICATION MONITORS TO INTEGRATED CIRCUIT CHIPS

Title (de)
VERFAHREN ZUM HINZUFÜGEN VON HERSTELLUNGSÜBERWACHUNGSVORRICHTUNGEN ZU INTEGRIERTEN SCHALTUNGSSCHIPS

Title (fr)
PROCEDE D'ADJONCTION DE MONITEURS DE FABRICATION A DES MICROCIRCUITS INTEGRES

Publication
EP 1869595 A4 20091216 (EN)

Application
EP 05855609 A 20051222

Priority
• US 2005047083 W 20051222
• US 90749405 A 20050404

Abstract (en)
[origin: US2006225023A1] An integrated circuit, a method and a system for designing and a method fabricating the integrated circuit. The method including: (a) generating a photomask level design of an integrated circuit design of the integrated circuit, the photomask level design comprising a multiplicity of integrated circuit element shapes; (b) designating regions of the photomask level design between adjacent integrated circuit element shapes, the designated regions large enough to require placement of fill shapes between the adjacent integrated circuit elements based on fill shape rules, the fill shapes not required for the operation of the integrated circuit; and (c) placing one or more monitor structure shapes of a monitor structure in at least one of the designated regions, the monitor structure not required for the operation of the integrated circuit.

IPC 8 full level
G03F 1/00 (2006.01); **G06F 17/50** (2006.01)

CPC (source: EP US)
H01L 22/20 (2013.01 - EP US); **H01L 2924/0002** (2013.01 - EP US)

Citation (search report)
• [XA] US 6808944 B1 20041026 - JIN BO [US], et al
• [X] US 6774395 B1 20040810 - LIN HUNG-JEN [US], et al
• [X] US 2004255259 A1 20041216 - TAN PATRICK [SG], et al
• [A] US 2003193050 A1 20031016 - PARK JEONG-HEON [KR], et al
• [A] US 6504225 B1 20030107 - MCCARTHY MICHAEL [US], et al
• See references of WO 2006107356A2

Designated contracting state (EPC)
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DOCDB simple family (publication)
US 2006225023 A1 20061005; US 7240322 B2 20070703; CN 101147148 A 20080319; CN 101147148 B 20100707; EP 1869595 A2 20071226; EP 1869595 A4 20091216; EP 1869595 B1 20130807; JP 2008535239 A 20080828; JP 5052501 B2 20121017; TW 200705229 A 20070201; TW I362598 B 20120421; US 2007160920 A1 20070712; US 2008017857 A1 20080124; US 7323278 B2 20080129; US 7620931 B2 20091117; WO 2006107356 A2 20061012; WO 2006107356 A3 20071122

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US 90749405 A 20050404; CN 200580049261 A 20051222; EP 05855609 A 20051222; JP 2008504019 A 20051222; TW 95111771 A 20060403; US 2005047083 W 20051222; US 68773107 A 20070319; US 85989007 A 20070924